

# Gathering the Best of HPC in Asia

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# SPONSORSHIP BROCHURE

11 to 14 March 2019

Suntec Singapore Convention & Exhibition Centre

SINGAPORE

SCA19 GUEST-OF-HONOUR MR HENG SWEE KEAT, MINISTER FOR FINANCE

Organised by



POWERING INNOVATION

SUPERCOMPUTING IN ASIA

1 Fusionopolis Way, Connexis South Tower, #17-01, Singapore 138632





# WHY SPONSOR?

Organised by NSCC Singapore, SupercomputingAsia (SCA) is an annual international conference that encompasses an umbrella of notable supercomputing events with the key objective of promoting a vibrant and relevant HPC ecosystem in Singapore. The second edition of SCA will be held from 11 to 14 March 2019 at Suntec Singapore Convention & Exhibition Centre.

SCA is attended by mid and C-level executives, principal researchers and HPC professionals from academia, industry and government organisations. SCA18 has proven to be a platform for delegates and exhibitors to gain access to visionary insights from thought leaders, optimum networking opportunities and the HPC community in Singapore, Asia and beyond.

# **SCA18 HIGHLIGHTS**

Attended by over 800 delegates from more than 24 countries



Opening Keynote Speaker, Keynote Speaker, Dr Goh Eng Lim, VP & Dr Satoshi Sekigu CTO, HPC and AI, Hewlett Packard Enterprise Department of Info



Keynote Speaker, Dr Satoshi Sekiguchi, VP, Director General, Department of Information Technology and Human Factors, National Institute of Advanced Industrial Science and Technology (AIST), Japan



Guest-Of-Honour, Dr Janil Puthucheary, Senior Minister of State, Ministry of Communications and Information, Singapore



Inaugural SCA18 Awards

**Supercomputing Frontiers** 

Asia (SCFA), the technical

sessions for SCA18 that

# **SCA18 SUCCESSES**

- Co-location of the Asia Pacific Advanced Network Meeting (APAN45), the largest and longest-standing community of advanced network experts that pioneers and strategises research network connectivity and platforms for research and innovative projects in Asia Pacific.
- The Asia Pacific Research Platform (APRP) co-located event was also held in conjunction with APAN, where HPC and networking experts knocked heads together to lay the groundwork for building the planned Asia Pacific Research Platform which is another innovation to bridge researchers and HPC/networking facilities over a large geographical region.
- received over 40 quality papers, out of which 16 were presented in the areas of Big Data, Graphics PRAN, where peads together to need Asia Pacific ovation to bridge es over a large
- Industry sessions proved popular with over 300 attendees attending the planned talks over the 3-day conference programme, including pre-conference tutorial sessions.
- The inaugural Conference on Next Generation
   Arithmetic (CoNGA) event discussed a new innovation
   invented by supercomputing veteren Professor John
   Gustafson, and whose latest unum incarnation called
   "posits" has the potential of changing the entire
   computing landscape.

## **CUSTOMISED PACKAGE**



For sponsorships opportunities beyond S\$30,000, talk to us to personalise a package best suited for your organisation's needs.

For enquiries, please connect with us at sponsorships@sc-asia.org

### SPONSORSHIP PACKAGES

NOTE: Sponsorship slots are on a first-come-first-served basis.

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# SPONSORSHIP PACKAGE ENTITLEMENTS













#### **Exhibition Booth Spaces**

(raw space for build up by sponsor) (inclusive of the following per one (1) space)











- · One (1) floor space of 2m x 2m area with 4 panels. Panel size is 1m(W) x 2.5m(H).
- · One (1) display table with table cloth, skirting and 2 chairs.
- · One (1) unit of 4 gangway 13-amp power point.

#### **Speaking and Presentation Slots**

Topics for all speaking and presentation slots must be approved by the organising committee









**Presentation Slot in Industry Track** 









#### **Types of Passes**

networking events













#### **Complimentary Exhibitor Passes**

\* Access to exhibition hall only













#### **Logo Exposure**

One (1) Logo with acknowledgement in all conference materials.













#### **Promotional Materials**

One (1) Corporate brochure insertion (max. A4 size) and corporate gift in conference bag.









# SPONSORSHIP AGREEMENT FORM

Please email completed and signed form to: **sponsorships@sc-asia.org**An online copy can also be download via **www.sc-asia.org** 

Contact Informa	ation (Please fill in accordingly):
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Sponsorship Fackages	3GD (\$) 11CH
Language Customised Package	
Diamond Package	
Platinum Package	20,000
Gold Package   Go	10,000
Silver Package	
Exhibitor Package	3,000

For all payment settlement and enquiries, please contact **secretariat@sc-asia.org** 

#### Terms & Conditions:

Office Phone

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- All indicated costs exclude 7% Goods and Services Tax.
- Sponsorship slots are available on a first-come-first-served basis.
- Selection of booth is available only after payment has been made and received by the organisers.
  Exhibitors and sponsors will be given access to the online exhibition portal thereafter.
- · Booth customisation and hardware add-ons are available for purchase within the exhibition portal.
- The organisers have the sole right to exercise discretion for all matters related to exhibiting at SupercomputingAsia 2019.

I / We agree to the ab	pove terms and conditions and confirm the above agreement.	
Signature of Represe	entative	
Name of Signatory:		
Date:		